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SAMSUNG ELECTRONICS CO LTD	*KR 2001054744-A	
1999.12.08 1999-055695(+1999KR-055695) (2001.07.02) H01L 23/02		
Fine pitch ball grid array Package including beam lead with containing couple bonding part		
C2002-042181		
Addnl. Data: CHOI G W, SONG Y H		

#### NOVELTY

An FBGA (Fine pitch Ball Grid Array) package including beam lead with containing couple bonding part id provided to prevent badness such as electrical disconnection due to a damage of a beam lead.

#### DETAILED DESCRIPTION

An FBGA(Fine pitch Ball Grid Array) package(200) is composed of a semiconductor chip(110), a carbon polymer(120), a tape for FBGA(150), and an external connection terminal(160) such as a solder ball. Bonding pads(112) are formed on the active surface of semiconductor chip(110), and the carbon polymer(120) is doped. The FBGA(150) tape is attached on the carbon polymer(120). The FBGA tape(150) consists of a polyimide film(130) and beam leads(140). An open aperture(134) is made in the polyimide film(130) for loading a

A(S-J1B, 12-E7C) L(4-C17A, 4-C20A, 4-F2)

150 { 180  
140  
120  
110  
112  
170  
134  
142  
147  
148  
132  
200

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